"TABLE 1"

DRAWING (NEW NO.)	DRAWING (OLD NO.)	CIRCUIT	TIP SPRING	RING SPRING	SHUNT TERMINAL A	SHUNT TERMINAL B
2SJ-01011D21	SJ-101-Au	FIG. 2	1	1		1
2SJ-01021D21	SJ-102-Au	FIG. 3	1	1	1	
2SJ-01031D21	SJ-103-Au	FIG. 4	1	1		
2SJ-01041D21	SJ-104-Au	FIG. 5	1		1	
2SJ-01051D21	SJ-105-Au	FIG. 6	1			

REV.	ECN NO OR DESCRIPTION	REVISED	DATE
D	△1 料號瘦身，ECN NO.:T0900047	KENSON	8/25'09

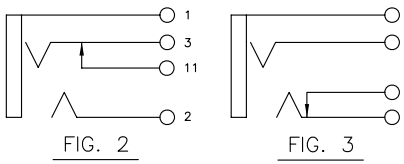


FIG. 2

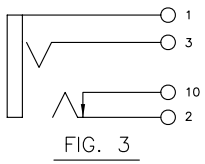


FIG. 3

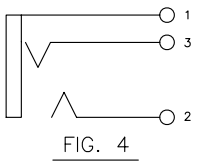


FIG. 4

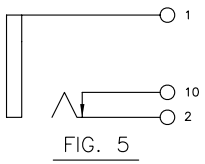


FIG. 5

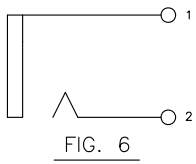
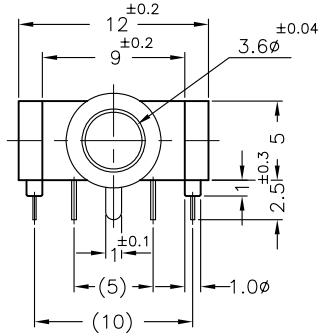
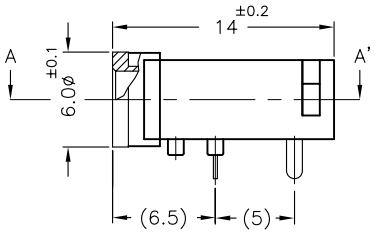
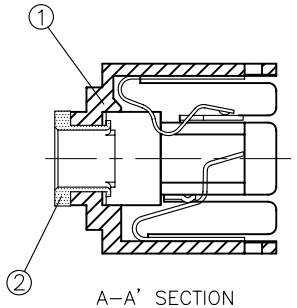


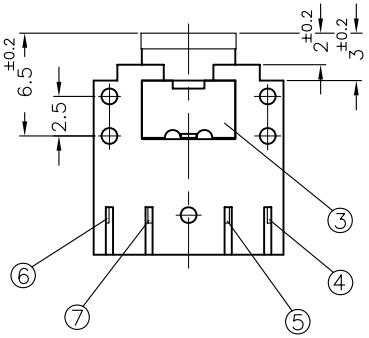
FIG. 6

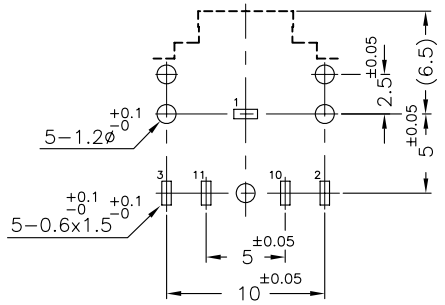






A-A' SECTION





P.C. BOARD

SPECIFICATIONS:

1. RATING: DC 12V 0.5A
2. INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHALL NOT BE LESS THAN 100MΩ MEASURED BY 500 VDC MEGGER.
3. CONTACT RESISTANCE: 30mΩ MAX.
4. INSULATION VOLTAGE WITHSTAND: 500VAC FOR ONE MINUTE.
5. AFTER EXPOSED AT TEMPERATURE OF 40°±2°C AND AT RELATIVE HUMIDITY OF 90%-95% FOR 96HOURS AND DRIED AT ROOM TEMPERATURE FOR 30 MINUTES, JACK SHALL BE SATISFIED ITEMS 2, 3.
6. LIFE TEST: 5,000 CYCLES MIN.
7. INSERTION FORCE:0.4-3Kg. AFTER LIFE TEST 0.3-3Kg.
8. WITHDRAWAL FORCE: 0.4-3Kg. AFTER LIFE TEST 0.3-3Kg.
9. MEASURING CONDITION:
   TEMPERATURE: FROM 5°C TO 35°C.
   RELATIVE HUMIDITY: FROM 40% TO 85%.
10. AFTER LIFE TEST, CONTACT RESISTANCE: 100mΩ MAX.
11. AFTER HUMIDITY TEST, INSULATION RESISTANCE: 50MΩ. MIN.

NO	DESCRIPTION	QTY	MATERIAL	PLATING&COLOR
7	SHUNT TERMINAL-B	*	BRASS 0.3t	GOLD FLASH
6	RING SPRING	*	COPPER ALLOY 0.2t	GOLD FLASH
5	SHUNT TERMINAL-A	*	BRASS 0.3t	GOLD FLASH
4	TIP SPRING	*	COPPER ALLOY 0.25t	GOLD FLASH
3	EARTH TERMINAL	1	PHOSPHOR BRONZE 0.25t	GOLD FLASH
2	METAL	1	BRASS	GOLD FLASH
1	BODY	1	PBT UL 94V-0	BLACK COLOR

UNLESS OTHERWISE SPECIFED TOLERANCES

DECIMALS: X :±0.3, X.X :±0.2, X.XX :±0.1, X.XXX :±0.05

ANGLES: X :±1°, X.X :±0.5°

Singatron Electronic(Chung-Shan) Co., Ltd.
信電子(中山)有限公司

TITEL	3.5ø PHONE JACK			
DWN	KENSON 8/25'09	PART NO. 2SJ-010 □1D21		
CHKD	HARVEY 8/25'09	SCALE: N/A	UNIT: mm	
APVD	ROBIN 8/25'09	SIZE: A3	SHEET: 1OF1	REV: D

ENGINEERING COPY

文件編號:RD-06-035-2A